

HD74LS75

Quadruple Bistable Latches

REJ03D0416-0300

Rev.3.00

May 10, 2006

The HD74LS75 is ideally suited for use as temporary storage for binary information between processing units and input / output or indicator units. Information present at a data (D) input is transferred to the Q output when the enable (G) is high and the Q output will follow the data input as long as the enable remains high. When the enable goes low, the information (that was present at the data input at the time the transition occurred) is retained at the Q output until the enable is permitted to go high. This device features complementary Q and \bar{Q} outputs from a 4-bit latch.

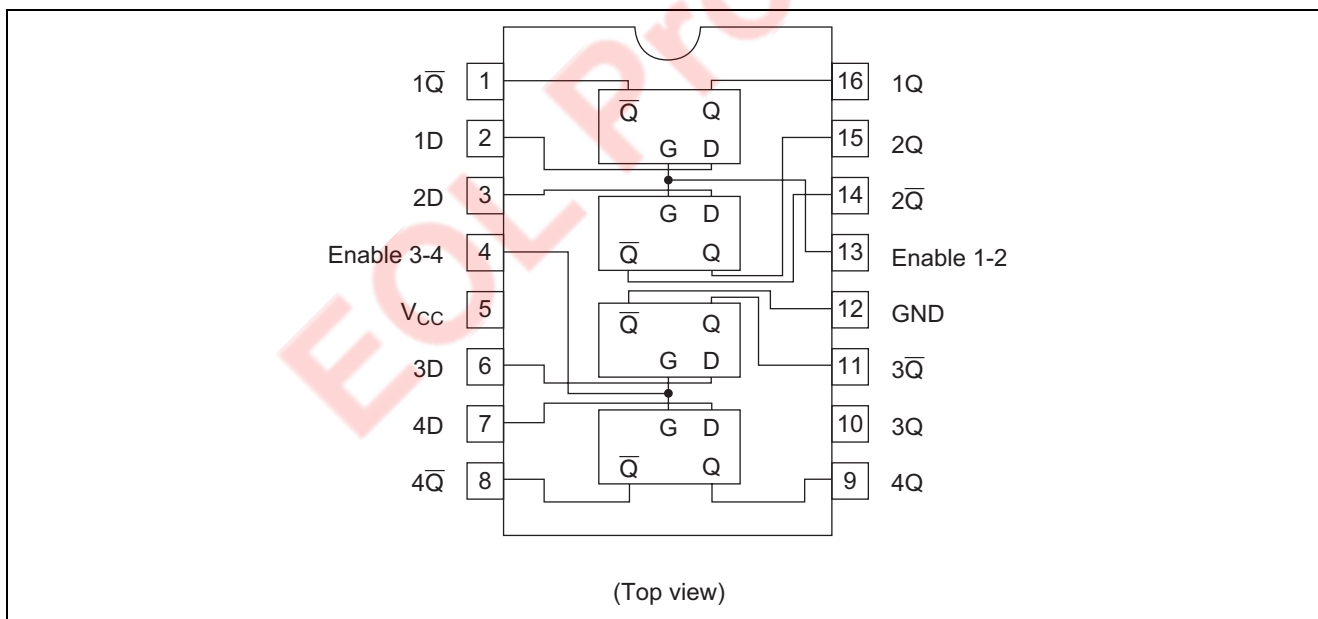
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS75P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74LS75FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Function Table

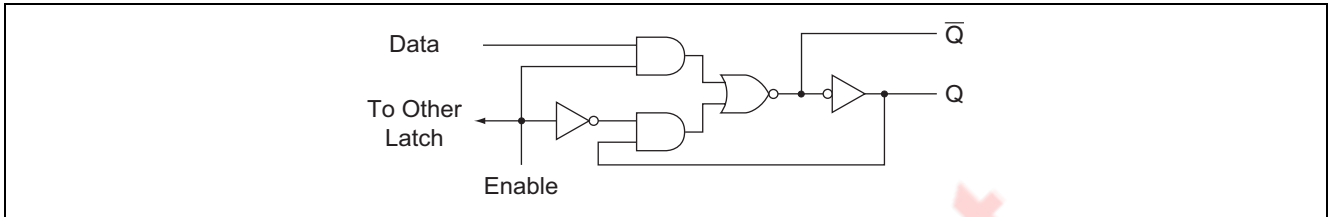
Inputs		Outputs	
D	G	Q	\bar{Q}
L	H	L	H
H	H	H	L
X	L	Q ₀	\bar{Q}_0

H; high level, L; low level, X; irrelevant

Q₀; level of Q before the indicated steady-state input conditions were established.

\bar{Q}_0 ; complement of Q₀ or level of \bar{Q}_0 before the indicated steady-state input conditions were established.

Circuit Schematic (1/4)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V _{CC}	7	V
Input voltage	V _{IN}	7	V
Power dissipation	P _T	400	mW
Storage temperature	T _{stg}	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V _{CC}	4.75	5.00	5.25	V
Output current	I _{OH}	—	—	-400	μA
	I _{OL}	—	—	8	mA
Operating temperature	T _{opr}	-20	25	75	°C
Pulse width	t _w	20	—	—	ns
Setup time	t _{su}	15	—	—	ns
Hold time	t _h	5	—	—	ns

Electrical Characteristics

(Ta = -20 to +75 °C)

Item		Symbol	min.	typ.*	max.	Unit	Condition
Input voltage		V _{IH}	2.0	—	—	V	
		V _{IL}	—	—	0.8	V	
Output voltage		V _{OH}	2.7	—	—	V	V _{CC} = 4.75 V, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -400 μA
		V _{OL}	—	—	0.4	V	V _{CC} = 4.75 V, V _{IH} = 2 V, V _{IL} = 0.8 V
—	—		0.5				
Input current	D input	I _{IH}	—	—	20	μA	V _{CC} = 5.25 V, V _I = 2.7 V
	G input		—	—	80		
	D input	I _{IL}	—	—	-0.4	mA	
	G input		—	—	-1.6		
	D input	I _I	—	—	0.1	mA	
	G input		—	—	0.4		
Short-circuit output current		I _{OS}	-20	—	-100	mA	V _{CC} = 5.25 V
Supply current**		I _{CC}	—	6.3	12	mA	V _{CC} = 5.25 V
Input clamp voltage		V _{IK}	—	—	-1.5	V	V _{CC} = 4.75 V, I _{IN} = -18 mA

Notes: * V_{CC} = 5 V, Ta = 25°C** I_{CC} is measured with all outputs open and all inputs grounded.

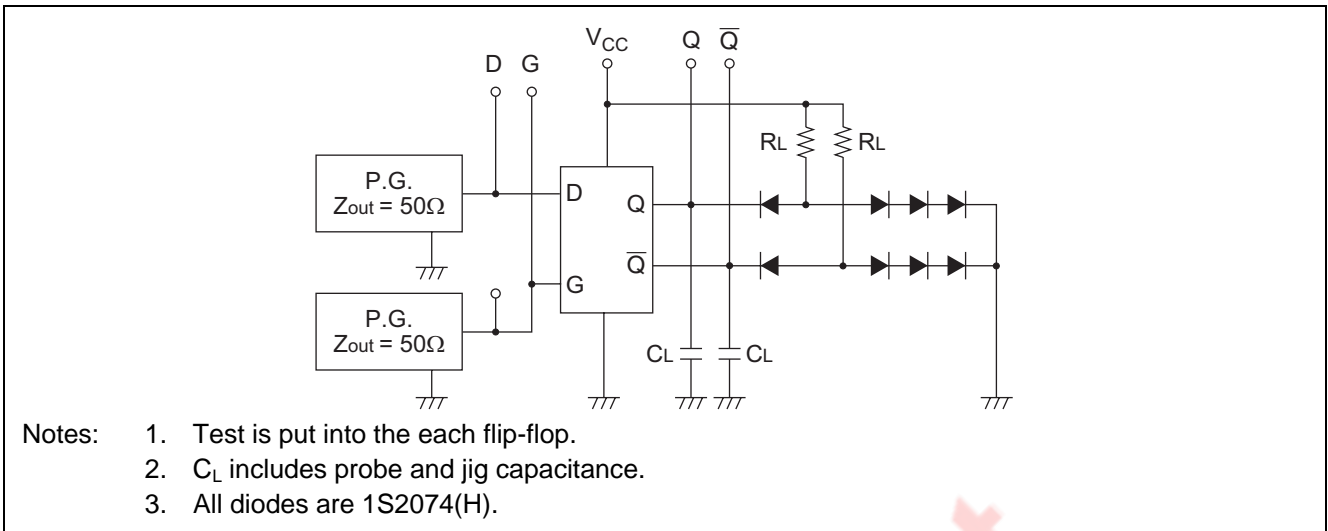
Switching Characteristics

(V_{CC} = 5 V, Ta = 25°C)

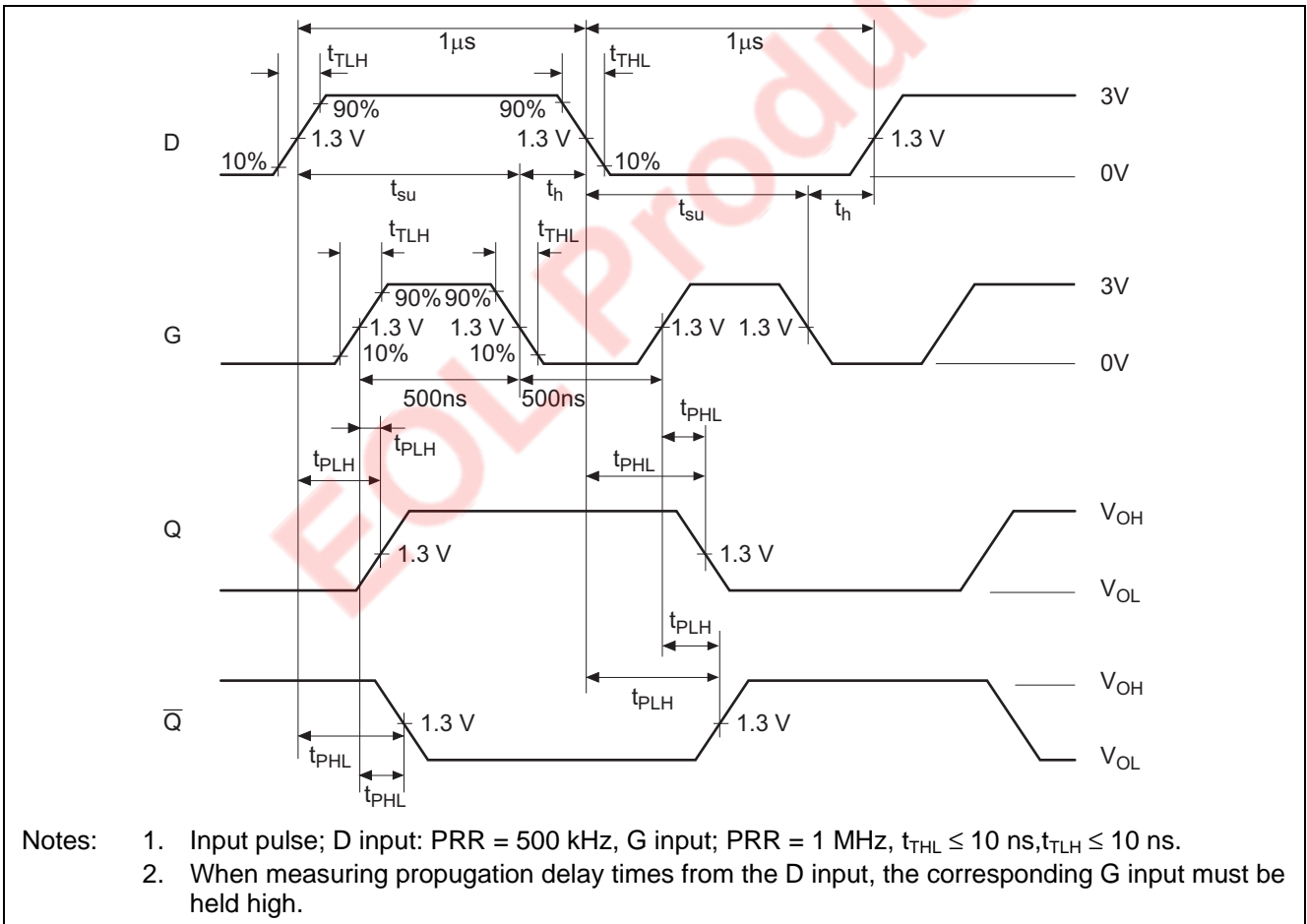
Item	Symbol	Inputs	Outputs	min.	typ.	max.	Unit	Condition
Propagation delay time	t _{PLH}	D	Q	—	15	27	ns	C _L = 15 pF, R _L = 2 kΩ
	t _{PHL}			—	9	17		
	t _{PLH}	D	\bar{Q}	—	12	20	ns	
	t _{PHL}			—	7	15		
	t _{PLH}	G	Q	—	15	27	ns	
	t _{PHL}			—	14	25		
	t _{PLH}	G	\bar{Q}	—	16	30	ns	
	t _{PHL}			—	7	15		

Testing Method

Test Circuit

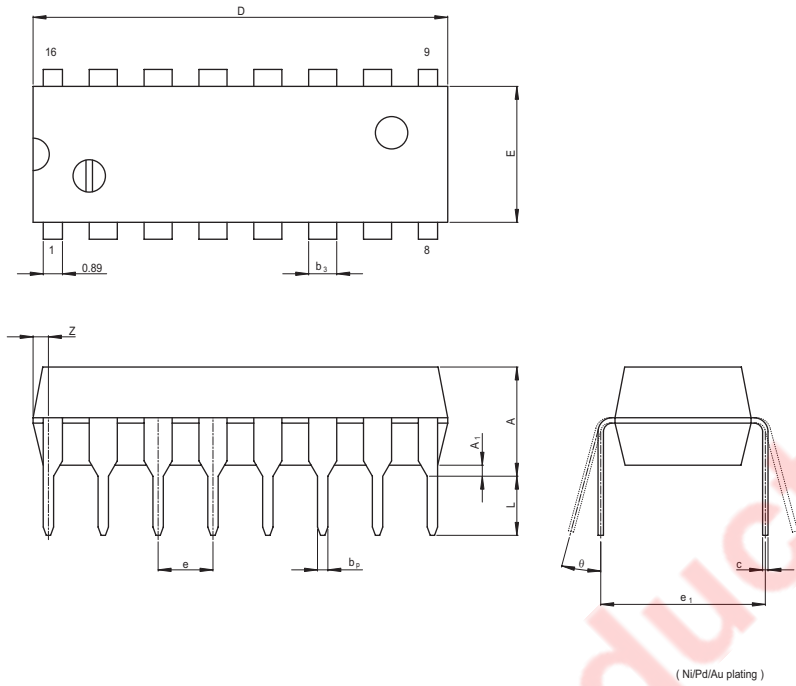


Waveform



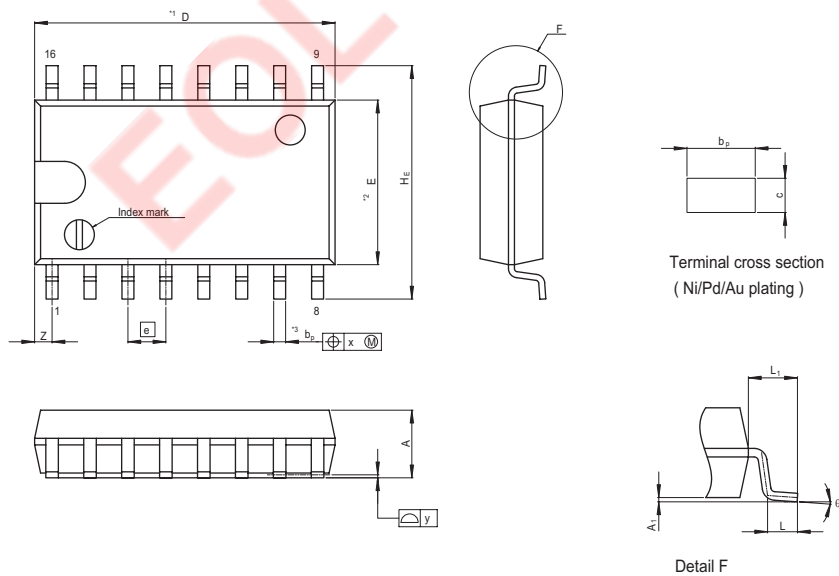
Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP16-6.3x19.2-2.54	PRDP0016AE-B	DP-16FV	1.05g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e ₁	—	7.62	—
D	—	19.2	20.32
E	—	6.3	7.4
A	—	—	5.06
A ₁	0.51	—	—
b _p	0.40	0.48	0.56
b ₃	—	1.30	—
c	0.19	0.25	0.31
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	1.12
L	2.54	—	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP16-5.5x10.06-1.27	PRSP0016DH-B	FP-16DAV	0.24g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	10.06	10.5
E	—	5.50	—
A ₂	—	—	—
A ₁	0.00	0.10	0.20
A	—	—	2.20
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	7.50	7.80	8.00
⊙	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L ₁	—	1.15	—

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Renesas Technology America, Inc.

450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd.

Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

Renesas Technology Hong Kong Ltd.

7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.

10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd.

1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.

Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510